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P.D.
2/12/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/756,971
Filing Date January 9, 2001
Inventor Salman Akram
Assignee Micron Technology, Inc.
Group Art Unit 2812
Examiner Jones, J.
Attorney's Docket No. MI22-1572
Title: Methods of Forming Board-On-Chip Packages

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

To: Assistant Commissioner for Patents
Washington, D.C. 20231

From: David G. Latwesen, Ph.D.
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TC 2800 MAIL ROOM
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U.S. PATENT AND TRADEMARK OFFICE

Dear Sir:

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449 and copies of which are attached.

Citation of these references is respectfully requested.

A check in the amount of \$180.00 is enclosed to cover the fee specified under 37 C.F.R. § 1.17(p).

AMERICAN INGENUITY 09756971

180.00 OP

Dated: 1/29/02

Respectfully submitted,

By: David G. Latwesen, Ph.D.

Reg. No. 38,533